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Intel - 5SGXMB6R2F40C1N Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Betans	
Product Status	Obsolete
Number of LABs/CLBs	225400
Number of Logic Elements/Cells	597000
Total RAM Bits	53248000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-FBGA (40x40)
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxmb6r2f40c1n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I 3YY	14
3		Yes	Yes	Yes		Yes	Yes (4)	Yes
GX channel—8.5 Gbps		165	165	165		163	163 17	165

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices. **Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering** ⁽¹⁾, ⁽²⁾

Transaction Oracle Oracle	Core Speed Grade				
Transceiver Speed Grade	C1	C2	12	13	
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_	
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes	

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3.	Absolute	Maximum	Ratings	for Stratix \	/ Devices	(Part 1 of 2)
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Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
+	Power supply ramp time	Standard POR	200 µs	_	100 ms	—
LRAMP	Power supply ramp time	Fast POR	200 µs		4 ms	_

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Notes to Table 6:

(1) V_{CCPD} must be 2.5 V when V_{CCI0} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCI0} is 3.0 V.

(2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.

(3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.

(4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	un, uo, ui	2.375	2.5	2.625	v
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
(1), (3)	side)	ux, us	2.375	2.5	2.625	v
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	
V _{CCR_GXBL}	Pacaivar analog powar supply (left side)		0.87	0.90	0.93	V
(2)	Receiver analog power supply (left side)	GX, GS, GT	0.97	1.0	1.03	v
			1.03	1.05	1.07	

Table 8 shows the transceiver power supply voltage requirements for various conditions.

Table 8. Transceiver Power Supply Voltage Requirements

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB ⁽²⁾	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:	All	1.05			
 Data rate > 10.3 Gbps. DFE is used. 	All	1.05			
If ANY of the following conditions are true ⁽¹⁾ :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true:ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
 DFE, AEQ, and EyeQ are not used. 					

Notes to Table 8:

(1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

(2) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	
dR/dT		1.8	0.266	%/°C
		1.5	0.273	
		1.2	0.317	

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2)⁽¹⁾

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	рF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	рF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15.	Hot Socketing Specifications for Stratix V Devices
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Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μA
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{10PIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

1/0 Stondard		V _{ccio} (V)			V _{REF} (V)			V _{TT} (V)	
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCI0}	0.5 * VCCIO	0.51 * V _{CCIO}
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCI0}	0.5 * V _{CCIO}	0.51 * V _{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCI0}	0.49 * V _{CCI0}	0.5 * VCCIO	0.51 * V _{CCIO}
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCI0}	0.5 * VCCIO	0.51 * V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V _{CCI0} /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V _{CCI0} /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V _{CCI0}	0.5 * V _{CCIO}	0.53 * V _{CCIO}	—	V _{CCI0} /2	
HSUL-12	1.14	1.2	1.3	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	—	_	_

Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Device	es
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Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices	(Part 1 of 2)
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I/O Standard	V _{IL(D(}	_{:)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{ol} (V)	V _{oh} (V)	L (mA)	I _{oh}
ijo Stalluaru	Min	Max	Min	Max	Max	Min	Max	Min	I _{ol} (mA)	(mÅ)
SSTL-2 Class I	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCI0} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCI0} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	V _{TT} – 0.603	V _{TT} + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCI0} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	0.28	V _{CCI0} – 0.28	13.4	-13.4
SSTL-15 Class I		V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCI0}	0.8 * V _{CCI0}	8	-8
SSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCI0}	0.8 * V _{CCI0}	16	-16
SSTL-135 Class I, II		V _{REF} – 0.09	V _{REF} + 0.09	_	V _{REF} – 0.16	V _{REF} + 0.16	0.2 * V _{CCI0}	0.8 * V _{CCI0}	_	_
SSTL-125 Class I, II		V _{REF} – 0.85	V _{REF} + 0.85	_	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCI0}	0.8 * V _{CCI0}	_	_
SSTL-12 Class I, II		V _{REF} – 0.1	V _{REF} + 0.1		V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}		_

I/O		V _{ccio} (V)		V _{DIF(}	_{DC)} (V)	V _{X(AC)} (V)				V _{CM(DC)} (V)	V _{DIF(AC)} (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCI0} + 0.3	—	0.5* V _{CCI0}	_	0.4* V _{CCI0}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCI0} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCI0} - 0.12	0.5* V _{CCIO}	0.5*V _{CCI0} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	_{cio} (V)	(10)		V _{ID} (mV) ⁽⁸⁾			V _{ICM(DC)} (V)		Vo	_D (V) (5)	V	_{осм} (V) ((6)
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Tran	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.									For				
2.5 V	2.375	2.5	2.625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375
LVDS ⁽¹⁾	2.375	2.0	2.025	100	1.25 V	_	1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_		—	_	_	_		_		
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) ⁽³⁾	2.375	2.5	2.625	200		600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4			_	300		_	0.6	D _{MAX} ≤ 700 Mbps	1.8		_	_			
), (9)		_		300	_	_	1	D _{MAX} > 700 Mbps	1.6		_	_			—

Notes to Table 22:

(1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

(2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.

(3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.

- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 V.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to 0.5	_	_	0 to 0.5		_	0 to 0.5	_	%
On-chip termination resistors ⁽²¹⁾	_	_	100		_	100		_	100		Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_		1.2		_	1.2	
Absolute V_{MIN}	—	-0.4	—		-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC	Dedicated reference clock pin	1050/	1000/90	00/850 ⁽²⁾	1050/	/1000/900/850 ⁽²⁾		1050/	00/850 ⁽²⁾	mV	
coupled) ⁽³⁾	RX reference clock pin	1.	.0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	1.0/0.9/0.85 ⁽⁴⁾			V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250		550	250		550	250		550	mV
	100 Hz	—	—	-70	—	—	-70	—	—	-70	dBc/Hz
Transmitter	1 kHz			-90			-90		—	-90	dBc/Hz
REFCLK Phase Noise	10 kHz	—	—	-100	—	—	-100	—	—	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz			-110	—	—	-110	—	—	-110	dBc/Hz
	≥1 MHz	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁷⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R _{REF} (19)	_		1800 ±1%		_	1800 ±1%	_		180 0 ±1%		Ω
Transceiver Clocks	S										
fixedclk clock frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 2 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trar	isceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1	_	2	_	_	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2	_	4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	—	dB
Transmitter											
Supported I/O Standards	_				-	I.4-V ar	nd 1.5-V PC	ML			
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600		12500	600		8500/ 10312.5 (24)	Mbps
	85-Ω setting		85 ± 20%	_	_	85 ± 20%		_	85 ± 20%	_	Ω
Differential on-	100-Ω setting	_	100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%			120 ± 20%		_	120 ± 20%		Ω
	150-Ω setting		150 ± 20%			150 ± 20%			150 ± 20%		Ω
V _{OCM} (AC coupled)	0.65-V setting		650		_	650		_	650	_	mV
V _{OCM} (DC coupled)	_		650		_	650		_	650	_	mV
Rise time (7)	20% to 80%	30		160	30		160	30		160	ps
Fall time ⁽⁷⁾	80% to 20%	30		160	30		160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps			15			15			15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode			120			120			120	ps

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 5 of 7)

Mada (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode ⁽²⁾	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	5	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	0	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Notes to Table 25:

(1) The maximum data rate is in Gbps.

(2) The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

(3) The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)⁽¹⁾

Symbol/	Conditions		Transceive Speed Grade			Fransceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	Ī
	100 Hz			-70			-70	
Transmitter REFCLK	1 kHz		_	-90	_	_	-90	-
Phase Noise (622	10 kHz		_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz		—	-110	_	—	-110	-
	\geq 1 MHz		—	-120	_	—	-120	-
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCIe)		_	3	_		3	ps (rms)
RREF ⁽¹⁷⁾	—		1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	MHz
Receiver				•				
Supported I/O Standards	—		1.4-V PCMI	_, 1.5-V PCM	L, 2.5-V PCI	ML, LVPEC	L, and LVDS	3
Data rate (Standard PCS) ⁽²¹⁾	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) ⁽²¹⁾	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4		_	V
Maximum peak-to-peak	GT channels	_	—	1.6	—	—	1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration (¹⁶), (²⁰)	V _{CCR_GTB} = 1.05 V (V _{ICM} = 0.65 V)	—	-	2.2	_	_	2.2	V
oomguration (), ()	GX channels		•	•	(8)			
Minimum differential	GT channels	200	_		200			mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Table 29 shows the V_{OD} settings for the GT channel.

Table 29.	Typical Von Setting	g for GT Channel, 1	EX Termination = 100 Ω
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Symbol	V _{OD} Setting	V _{op} Value (mV)
	0	0
	1	200
\mathbf{V}_{0D} differential peak to peak typical (1)	2	400
VOD unicicilitat peak to peak typical (*)	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance					
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit		
Global and Regional Clock	717	650	580	MHz		
Periphery Clock	550	500	500	MHz		

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Gumbal	Oenditione		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I 3 YY		C4,I	4	Unit
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)	_	(8)	(6)		(8)	(6)		(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
DPA Mode														
DPA run length	_			1000 0		_	1000 0		_	1000 0		_	1000 0	UI
Soft CDR mode)													
Soft-CDR PPM tolerance	_	_	_	300	_	—	300	_		300	_		300	± PPM
Non DPA Mode	•	•		-		-		•		-			-	-
Sampling Window	_			300			300			300			300	ps

Table 36. High-Speed I/O Specifications for Stratix V Devices ^{(1), (2)} (Part 4 of 4)

Notes to Table 36:

(1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.

(2) When J = 1 or 2, bypass the SERDES block.

(3) This only applies to DPA and soft-CDR modes.

(4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

(5) This is achieved by using the **LVDS** clock network.

(6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.

(8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

(9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.

(10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.

(11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.

(12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.

(13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.

(14) Requires package skew compensation with PCB trace length.

(15) Do not mix single-ended I/O buffer within LVDS I/O bank.

(16) Chip-to-chip communication only with a maximum load of 5 pF.

(17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins (1)

Symbol	C1		C2, C2L, I2, I2L			3, I3L, Syy	C4,I4		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Note to Table 44:

(1) The DCD numbers do not cover the core clock network.

Configuration Specification

POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification (1)

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

Note to Table 45:

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period ⁽²⁾	30	—	ns
t _{JCP}	TCK clock period ⁽²⁾	167	—	ns
t _{JCH}	TCK clock high time ⁽²⁾	14	—	ns
t _{JCL}	TCK clock low time ⁽²⁾	14	—	ns
t _{JPSU (TDI)}	TDI JTAG port setup time	2	—	ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3	—	ns

Symbol	Description	Min	Max	Unit
t _{JPH}	JTAG port hold time	5	—	ns
t _{JPCO}	JTAG port clock to output	—	11 ⁽¹⁾	ns
t _{JPZX}	JTAG port high impedance to valid output	—	14 ⁽¹⁾	ns
t _{JPXZ}	JTAG port valid output to high impedance	—	1 4 ⁽¹⁾	ns

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Notes to Table 46:

(1) A 1 ns adder is required for each V_{CCI0} voltage step down from 3.0 V. For example, $t_{JPC0} = 12$ ns if V_{CCI0} of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.

(2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

Raw Binary File Size

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}	
	ECCVA2	H35, F40, F35 ⁽²⁾	213,798,880	562,392	
	5SGXA3	H29, F35 ⁽³⁾	137,598,880	564,504	
	5SGXA4	_	213,798,880	563,672	
	5SGXA5	_	269,979,008	562,392	
	5SGXA7	_	269,979,008	562,392	
Stratix V GX	5SGXA9	_	342,742,976	700,888	
	5SGXAB	_	342,742,976	700,888	
	5SGXB5	_	270,528,640	584,344	
	5SGXB6	_	270,528,640	584,344	
	5SGXB9	_	342,742,976	700,888	
	5SGXBB	_	342,742,976	700,888	
Stratix V GT	5SGTC5	_	269,979,008	562,392	
	5SGTC7	—	269,979,008	562,392	
	5SGSD3	_	137,598,880	564,504	
	5SGSD4	F1517	213,798,880	563,672	
Ctratic V CC	556504	_	137,598,880	564,504	
Stratix V GS	5SGSD5	_	213,798,880	563,672	
	5SGSD6	_	293,441,888	565,528	
	5SGSD8	_	293,441,888	565,528	

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}
Stratix V E ⁽¹⁾	5SEE9	—	342,742,976	700,888
	5SEEB	_	342,742,976	700,888

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Notes to Table 47:

(1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.

(2) 36-transceiver devices.

(3) 24-transceiver devices.

(4) File size for the periphery image.

(5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

• For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help.*

Table 48 lists the minimum configuration time estimates for Stratix V devices.

	Member		Active Serial ⁽¹⁾		Fast Passive Parallel ⁽²⁾				
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)		
	A3	4	100	0.534	32	100	0.067		
	AS	4	100	0.344	32	100	0.043		
	A4	4	100	0.534	32	100	0.067		
	A5	4	100	0.675	32	100	0.084		
	A7	4	100	0.675	32	100	0.084		
GX	A9	4	100	0.857	32	100	0.107		
	AB	4	100	0.857	32	100	0.107		
	B5	4	100	0.676	32	100	0.085		
	B6	4	100	0.676	32	100	0.085		
	B9	4	100	0.857	32	100	0.107		
	BB	4	100	0.857	32	100	0.107		
ст	C5	4	100	0.675	32	100	0.084		
GT	C7	4	100	0.675	32	100	0.084		

			Active Serial (1))	Fast Passive Parallel ⁽²⁾			
Variant	Variant Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	D3	4	100	0.344	32	100	0.043	
	D4	4	100	0.534	32	100	0.067	
GS	D4	4	100	0.344	32	100	0.043	
65	D5	4	100	0.534	32	100	0.067	
	D6	4	100	0.741	32	100	0.093	
	D8	4	100	0.741	32	100	0.093	
Е	E9	4	100	0.857	32	100	0.107	
	EB	4	100	0.857	32	100	0.107	

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Notes to Table 48:

(1) DCLK frequency of 100 MHz using external CLKUSR.

(2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[]ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[]ratio for each combination.

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
FFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
FPP ×10	Enabled	Disabled	4
	Enabled	Enabled	4

 Table 49. DCLK-to-DATA[] Ratio ⁽¹⁾ (Part 1 of 2)



Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA [] ratio. For the DCLK-to-DATA [] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52.	DCLK Frequency	Specification in the <i>l</i>	AS Configuration Scheme	(1), (2)
-----------	----------------	-------------------------------	-------------------------	----------

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Notes to Table 52:

(1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

(2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.





Notes to Figure 14:

- (1) If you are using AS $\times 4$ mode, this signal represents the AS_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
t _H	Data hold time after falling edge on DCLK	0	—	ns

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions	
G			
Н	_	_	
Ι			
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI t_{JCP} t_{JCH} t_{JCH} t_{JPCO} t_{JPCO} t_{JPXZ} TDO t_{JPXZ} t_{JPXZ}	
K L M N O	_	_	
Ρ	PLL Specifications	Diagram of PLL Specifications (1)	
Q		_	
	1	Receiver differential input discrete resistor (external to the Stratix V device).	